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Part Number: [0432498911](#)
Status: **Active**
Overview: [modular_plugs_jacks](#)
Description: Modular Jack, Right Angle, Low Profile, 8/10, Panel Stops

Documents:

3D Model	Product Specification PSX-43249 (PDF)
Drawing (PDF)	RoHS Certificate of Compliance (PDF)

Agency Certification

CSA	LR19980
UL	E107635

General

Product Family	Modular Jacks/Plugs
Series	43249
Component Type	PCB Jack
Magnetic	No
Overview	modular_plugs_jacks
Performance Category	3, 4
Power over Ethernet (PoE)	N/A
Product Name	RJ45

Physical

Boot Color	N/A
Color - Resin	Black
Durability (mating cycles max)	500
Flammability	94V-0
Inverted / Top Latch	No
Lightpipes/LEDs	None
Material - Metal	Brass, Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Orientation	Right Angle (Side Entry)
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.062 In
PCB Thickness Recommended (mm)	1.57 mm
Packaging Type	Tray
Pitch - Mating Interface (in)	0.040 In
Pitch - Mating Interface (mm)	1.02 mm
Pitch - Term. Interface (in)	0.050 In
Pitch - Term. Interface (mm)	1.27 mm
Plating min: Mating (µin)	50
Plating min: Mating (µm)	1.25
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.5
Ports	1
Positions / Loaded Contacts	8/10
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-40°C to +85°C
Termination Interface: Style	Through Hole
Waterproof / Dustproof	No
Wire/Cable Type	N/A

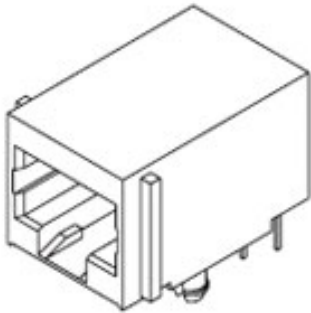


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Series

EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Contains SVHC: No
Halogen-Free
Status

China RoHS



Not Reviewed

**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series
[43249Series](#)

Mates With
FCC 68 Plugs

Electrical

Current - Maximum per Contact	1.5A
Grounding to PCB	Yes
Grounding to Panel	Yes
Shielded	Yes
Voltage - Maximum	150V AC (RMS)

Solder Process Data

Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-44050-004
Product Specification	PSX-43249
Sales Drawing	SDA-43249

This document was generated on 06/07/2010

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NOTES:

1) MATERIAL:

HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
INSULATOR: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE, .012/(0.30) THICK
SHIELD: BRASS, .007/(0.18) THICK

2) FINISH:

TERMINALS:

- A = SELECT GOLD IN CONTACT AREA: 50 MICROINCHES / 1.27 MICROMETERS MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
B = SELECT GOLD IN CONTACT AREA: 30 MICROINCHES / 0.76 MICROMETERS MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.

SHIELD:

- *100 MICROINCHES / 2.54 MICROMETERS NICKEL OVER 50 MICROINCHES /
1.27 MICROMETERS COPPER UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS
DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD
IN THE PC TAILS AND/OR SHIELD.

3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43249.

4) PACKAGING SPECIFICATION:

- UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
PER MOLEX PACKAGING SPECIFICATION PK-43249-004.
UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN TUBES
PER MOLEX PACKAGING SPECIFICATION PK-43249-005.
SHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
PER MOLEX PACKAGING SPECIFICATION PK-44050-004.

5) MATES WITH: MODULAR PLUGS THAT CONFORM TO FCC REGULATION PART 68.5.

6) SEE SHEET 3 FOR SHIELDED JACK ASSEMBLY.

7) SEE SHEETS 5 & 6 FOR P.C. BOARD LAYOUTS.

8) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.

9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

10) THIS PART CONFORMS TO FCC REGULATION 68.5 AND TIA 1096 FOR MODULAR JACKS.

SIDE/TOP GROUND TAB OPTIONS FOR SHIELDS



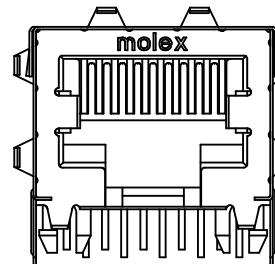
OPTION "A"
NO TOP OR SIDE TABS



OPTION "B"
TOP TABS

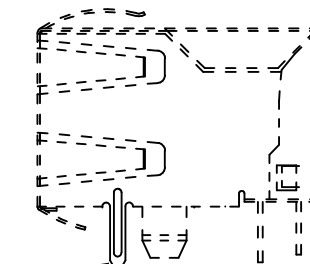


OPTION "C"
TOP AND STAGGERED SIDE TABS

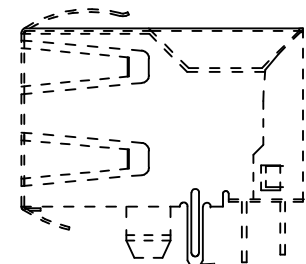


OPTION "D"
TOP AND SIDE TABS

BOTTOM PCB GROUND TAB OPTIONS FOR SHIELDS



OPTION "E"
OPTIONAL FRONT POSITION



OPTION "F"
OPTIONAL REAR POSITION

NOTE: EITHER PCB GROUND TAB OPTION IS AVAILABLE
ON ALL SIDE/TOP TAB CONFIGURATIONS

DRAWING LEGEND

- SHEET 1- NOTES, GROUND TAB OPTIONS
SHEET 2- UNSHIELDED MODULAR JACK
SHEET 3- SHIELDED MODULAR JACK WITH
OPTIONAL SIDE/TOP GROUND TABS & BOTTOM GROUND
TAB WITH OPTIONAL POSITION.
SHEET 4- PART NUMBER CHARTS
SHEET 5- FOOTPRINT LAYOUT FOR 8 POSITION HOUSING
SHEET 6- FOOTPRINT LAYOUT FOR 6 POSITION HOUSING

ADDED NOTE 10 EC NO: UCP2009-0740 DRWN: KLOSTERNER 2008/09/29 CHKD: JEBELL 2008/10/03 APPR: FSMITH 2008/10/03	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1/2°		DRAWN BY JTR DATE 1993/06/23 CHECKED BY JTR DATE 1993/06/23 APPROVED BY RAS DATE 1993/06/23		TITLE LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY			
						MOLEX INCORPORATED			
						MATERIAL NO. SEE SHEET 4	DOCUMENT NO. SDA-43249		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

UNSHIELDED MODULAR JACK

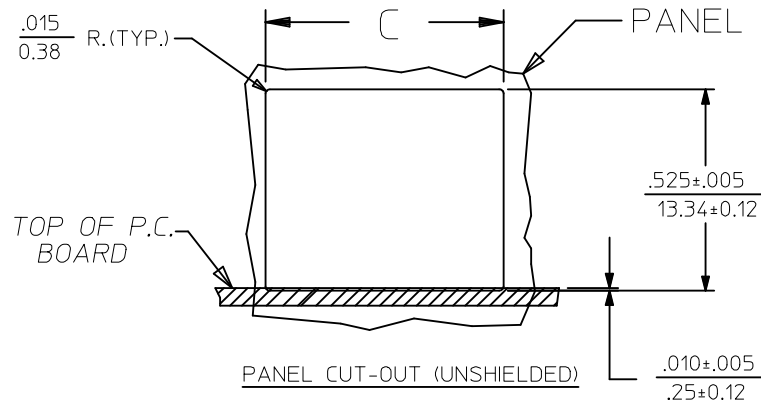
8 POSITION LOADED 10 SIZE SHOWN



OPTIONAL FLANGE
USED FOR FLUSH
MODULAR JACK



PEG DETAIL
SCALE 8:1

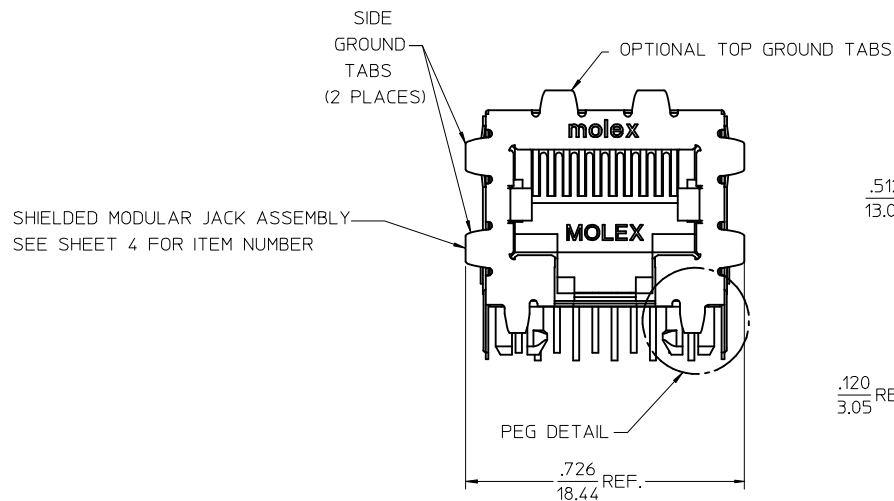


HOUSING SIZE	CIRCUIT SIZE	DIM. A	DIM. B	DIM. C
8	10	.600±.005 (15.24±0.13)	.450±.005 (11.43±0.13)	.620±.005 (15.75±0.13)
8	8	.600±.005 (15.24±0.13)	.350±.005 (8.89±0.13)	.620±.005 (15.75±0.13)
8	4	.600±.005 (15.24±0.13)	.150±.005 (3.81±0.13)	.620±.005 (15.75±0.13)
8	6	.600±.005 (15.24±0.13)	.250±.005 (6.35±0.13)	.620±.005 (15.75±0.13)
6	6	.520±.005 (13.21±0.13)	.250±.005 (6.35±0.13)	.540±.005 (13.72±0.13)
6	4	.520±.005 (13.21±0.13)	.150±.005 (3.81±0.13)	.540±.005 (13.72±0.13)
6	2	.520±.005 (13.21±0.13)	.050±.005 (1.27±0.13)	.540±.005 (13.72±0.13)

SEE SHEET 1 EC NO: UCP2009-0740 DRWN: JLOSTEME/ER 2008/09/29 CHKD: JBEL 2008/10/03 APPR: FSMITH 2008/10/03	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---		DRAWN BY JTR		DATE 1993/06/23		LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY	
		3 PLACES ± --- ± .010		CHECKED BY JTR		DATE 1993/06/23			
		2 PLACES ± 0.25 ± ---		APPROVED BY RAS		DATE 1993/06/23			
		1 PLACE ± --- ± ---		MATERIAL NO. RAS		DOCUMENT NO. SDA-43249			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 4		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SHEET NO. 2 OF 6			

MODULAR JACK W/ .007" THICK SHIELD AND OPTIONAL GROUND TABS

8 LOADED 10 VERSION SHOWN WITH GROUND TAB OPTIONS "D" AND "E"



PEG DETAIL
SCALE 8:1



DESCRIPTION OF GROUND TAB OPTIONS:
(SEE SHEET 4 FOR AVAILABLE COMBINATIONS OF OPTIONS)

GROUND TAB OPTION	DESCRIPTION
A	NO GROUND TABS
B	TOP TABS ONLY
C	STAGGERED SIDE TABS
D	TOP AND SIDE TABS
E	PCB GROUND TAB IN FRONT POSITION
F	PCB GROUND TAB IN REAR POSITION

HOUSING SIZE	CIRCUIT SIZE	B
8	10	.450 ± .005 11.43 ± 0.13
8	8	.350 ± .005 8.89 ± 0.13

SEE SHEET 1
EC NO: UCP2009-0740
DRWN: JLOSTEMEIER 2008/09/29
CHKD: JELL 2008/10/03
APPR: FSMITH 2008/10/03

QUALITY SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES ±	± .010	± .004
3 PLACES ±	± .010	± .004
2 PLACES ±	± .025	± .010
1 PLACE ±	± .050	± .020

ANGULAR ± 1/2°

DRAFT WHERE APPLICABLE
MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE
IN/MM

DRAWN BY DATE
JTR 1993/06/23

CHECKED BY DATE
JTR 1993/06/23

APPROVED BY DATE
RAS 1993/06/23

MATERIAL NO.
SEE SHEET 4

SIZE
C

SCALE
4:1

DESIGN UNITS
INCH

THIRD ANGLE PROJECTION

TITLE
LOW PROFILE RIGHT ANGLE
MODULAR JACK ASSEMBLY

MOLEX INCORPORATED

DOCUMENT NO.
SDA-43249

SHEET NO.
3 OF 6

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PC BOARD LAYOUT FOR SIZE 8, 10 CIRCUIT
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 8, 8 CIRCUIT
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 8, 6 CIRCUIT
(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062 ± .005 / (1.57 ± 0.13)

SEE SHEET 1 EC NO: UCP2009-0740 DRWN: KLOSTEMEIER 2008/09/29 CHKD: JELL 2008/10/03 APPR: FSMITH 2008/10/03	REV	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	TITLE LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY									
				mm	INCH														
					DRAWN BY JTR	DATE 1993/06/23													
K1	REV	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	4 PLACES ± --- ± ---		CHECKED BY JTR	DATE 1993/06/23	APPROVED BY RAS	DATE 1993/06/23	MATERIAL NO. RAS	DOCUMENT NO. SDA-43249	SHEET NO. 5 OF 6							
				3 PLACES ± --- ± .010															
				2 PLACES ± 0.25 ± ---															
				1 PLACE ± --- ± ---															
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				ANGULAR ± 1/2°		SEE SHEET 4		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											

13 12 11 10 9 8 7 6 5 4 3 2 1



PC BOARD LAYOUT FOR SIZE 6, 6 CIRCUIT
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 6, 4 CIRCUIT
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 6, 2 CIRCUIT
(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

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- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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